



SN74CBT3251 1-of-8 FET Multiplexer and Demultiplexer

1 Features

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Low Crosstalk Between Switches
- Fast Switching and Propagation Speeds
- Operating Temperature Range:
–40°C to 85°C

2 Applications

- Digital Radio
- Signal Gating
- Factory Automation
- Televisions
- Appliances
- Programmable Logic Circuits
- Sensors

3 Description

The SN74CBT3251 is a 1-of-8 high-speed TTL-compatible FET multiplexer and demultiplexer. The low ON-state resistance of the switch allows connections to be made with minimal propagation delay.

When output enable (\overline{OE}) is low, the SN74CBT3251 is enabled, and S0, S1, and S2 select one of the B outputs for the A-input data.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74CBT3251RGY	VQFN (16)	3.50 mm × 4.00 mm
SN74CBT3251DBQ	SSOP (16)	3.90 mm × 4.90 mm
SN74CBT3251PW	TSSOP (16)	4.40 mm × 5.00 mm
SN74CBT3251DB	SSOP (16)	5.30 mm × 6.20 mm
SN74CBT3251D	SOIC (16)	3.91 mm × 9.90 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Functional Diagram of the SN74CBT3251

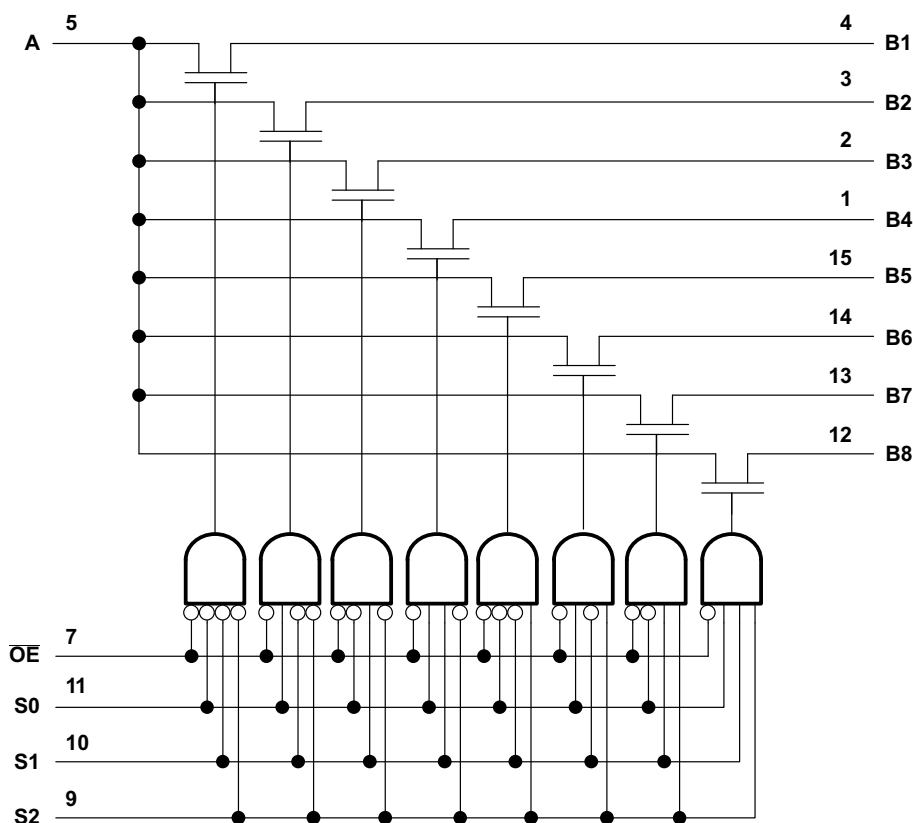


Table of Contents

1 Features	1	8.3 Feature Description.....	7
2 Applications	1	8.4 Device Functional Modes.....	7
3 Description	1	9 Application and Implementation	8
4 Revision History	2	9.1 Application Information.....	8
5 Pin Configuration and Functions	3	9.2 Typical Application	8
6 Specifications	4	10 Power Supply Recommendations	9
6.1 Absolute Maximum Ratings	4	11 Layout	9
6.2 ESD Ratings.....	4	11.1 Layout Guidelines	9
6.3 Recommended Operating Conditions.....	4	11.2 Layout Example	9
6.4 Thermal Information	4	12 Device and Documentation Support	10
6.5 Electrical Characteristics.....	5	12.1 Documentation Support	10
6.6 Switching Characteristics	5	12.2 Community Resources.....	10
6.7 Typical Characteristic.....	5	12.3 Trademarks	10
7 Parameter Measurement Information	6	12.4 Electrostatic Discharge Caution.....	10
8 Detailed Description	7	12.5 Glossary	10
8.1 Overview	7	13 Mechanical, Packaging, and Orderable Information	10
8.2 Functional Block Diagram	7		

4 Revision History

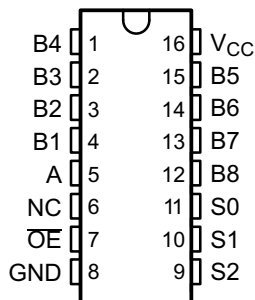
Changes from Revision L (January 2004) to Revision M

Page

- Added *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section. **1**

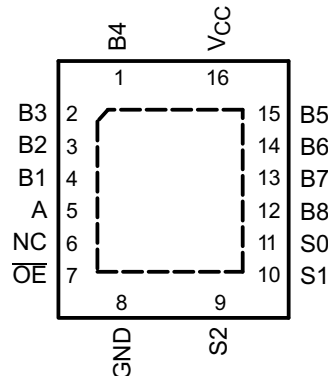
5 Pin Configuration and Functions

**D, DB, DBQ, or PW Packages
16-Pin SOIC, SSOP, or TSSOP
Top View**



NC – No internal connection

**RGY Package
16-Pin VQFN
Top View**



NC – No internal connection

Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	B4	I/O	Port B4
2	B3	I/O	Port B3
3	B2	I/O	Port B2
4	B1	I/O	Port B1
5	A	I/O	Common OUT/IN
6	NC	—	No Connect
7	\overline{OE}	I	Enable Ports (Active Low). See Table 1 .
8	GND	—	Ground
9	S2	I	Select Pin 2. See Table 1 .
10	S1	I	Select Pin 1. See Table 1 .
11	S0	I	Select Pin 0. See Table 1 .
12	B8	I/O	Port B8
13	B7	I/O	Port B7
14	B6	I/O	Port B6
15	B5	I/O	Port B5
16	V _{CC}	—	Power Pin

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

	MIN	MAX	UNIT
Supply voltage, V_{CC}	−0.5	7	V
Input voltage, V_I ⁽²⁾	−0.5	7	V
Continuous channel current		128	mA
Input clamp current, I_K ($V_{I/O} < 0$)		−50	mA
Maximum junction temperature, T_J		150	°C
Storage temperature, T_{stg}	−65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±1500
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	−40	85	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74CBT3251					UNIT
		D (SOIC)	DB (SSOP)	DBQ (SSOP)	PW (TSSOP)	RGY (VQFN)	
		16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	73 ⁽²⁾	82 ⁽²⁾	90 ⁽²⁾	108 ⁽²⁾	39 ⁽³⁾	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	70.6	49.0	59.0	41.6	52.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	77.8	49.4	50.1	51.9	20.4	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	24.3	10.5	13.9	4.0	1.1	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	77.4	48.8	49.7	51.3	20.4	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	—	—	—	—	6.4	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).
- (2) The package thermal impedance is calculated in accordance with JESD 51-7.
- (3) The package thermal impedance is calculated in accordance with JESD 51-5.

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
V_{IK}		$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.2	V
I_I		$V_{CC} = 5.5\text{ V}$, $V_I = 5.5\text{ V}$ or GND			±1	μA
I_{CC}		$V_{CC} = 5.5\text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
$\Delta I_{CC}^{(2)}$	Control inputs	$V_{CC} = 5.5\text{ V}$; One input at 3.4 V, other inputs at V_{CC} or GND			2.5	mA
C_i	Control inputs	$V_I = 3\text{ V}$ or 0		3.5		pF
$C_{io(OFF)}$	A port	$V_O = 3\text{ V}$ or 0, $\overline{OE} = V_{CC}$		17.5		pF
	B port	$V_O = 3\text{ V}$ or 0, $\overline{OE} = V_{CC}$		4		
$r_{on}^{(3)}$	$V_{CC} = 4\text{ V}$, TYP at $V_{CC} = 4\text{ V}$, $V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$			14	20	Ω
	$V_{CC} = 4.5\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$	5	7	
			$I_I = 30\text{ mA}$	5	7	
		$V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$		10	15	

(1) All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

(2) This is the increase in supply current for each input at the specified TTL voltage level, rather than V_{CC} or GND.

(3) Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

6.6 Switching Characteristics

over operating free-air temperature free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	MIN	MAX	UNIT
$t_{pd}^{(1)}$	A or B	B or A	$V_{CC} = 4\text{ V}$		0.35	ns
			$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		0.24	
t_{pd}	S	A	$V_{CC} = 4\text{ V}$		6	ns
			$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$	2	5.5	
t_{en}	S	B	$V_{CC} = 4\text{ V}$		6.4	ns
			$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$	1.5	5.6	
	\overline{OE}	A or B	$V_{CC} = 4\text{ V}$		6.4	
			$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$	1.6	5.8	
t_{dis}	S	B	$V_{CC} = 4\text{ V}$		6.8	ns
			$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$	1.9	6.4	
	\overline{OE}	A or B	$V_{CC} = 4\text{ V}$		6	
			$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$	2.3	6.2	

(1) The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

6.7 Typical Characteristic

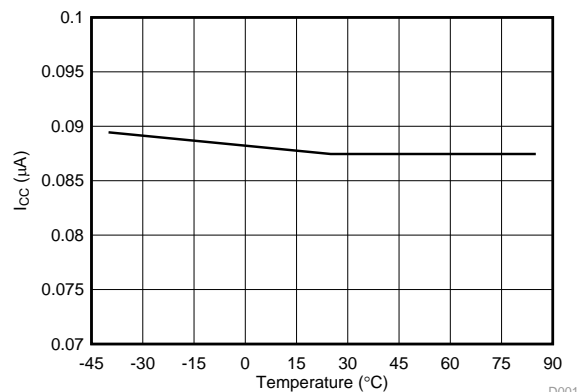
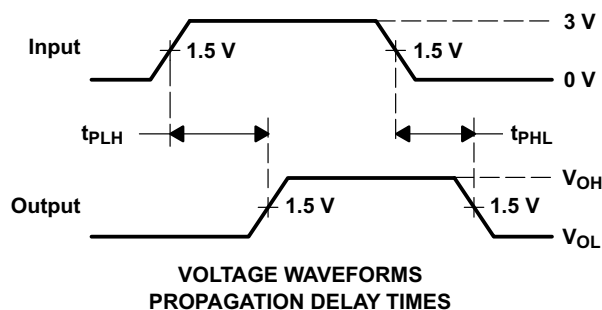
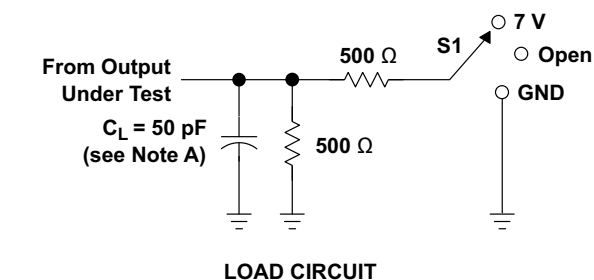
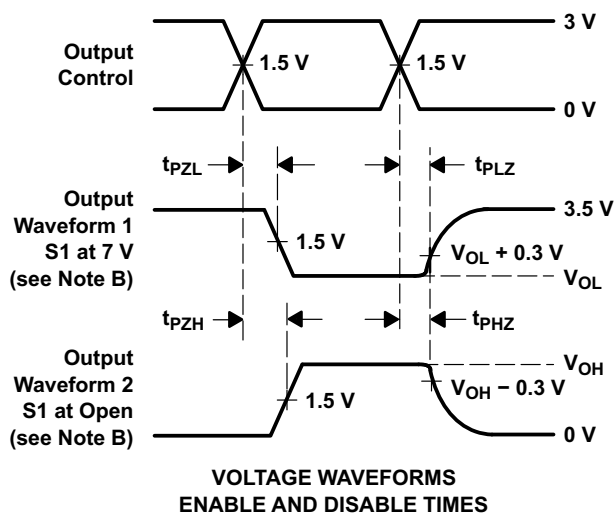


Figure 1. I_{CC} Variation With Temperature

7 Parameter Measurement Information



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

The SN74CBT3251 device is a single 8-channel multiplexer with three binary control inputs, S_0 , S_1 , and S_2 and an \overline{OE} (output enable, active low) input. The three binary signals select 1 of 8 channels to be turned on, and connect one of the 8 inputs to the output.

When they are used as demultiplexers, the CHANNEL IN/OUT terminals (B) are the outputs and the COMMON OUT/IN terminal (A) is the input.

8.2 Functional Block Diagram

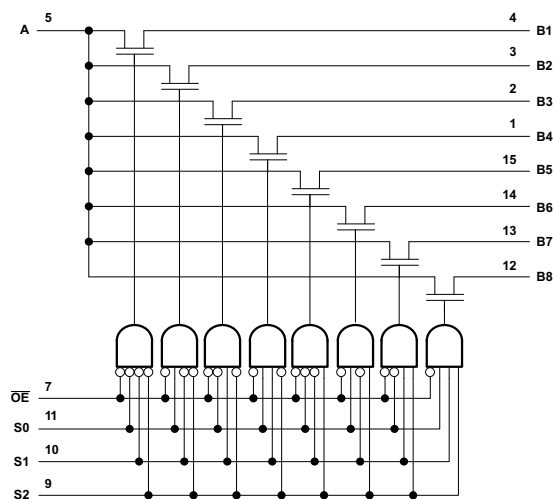


Figure 3. Logic Diagram (Positive Logic)

8.3 Feature Description

The SN74CBT3251 1-of-8 FET multiplexers and demultiplexers can accept a wide range of analog signal levels from 0 V to 5 V. It has low R_{on} resistance, typically 5- Ω for $V_{CC} = 5$ V which allows very little signal loss through the switch. Binary address decoding on chip makes channel selection easy.

8.4 Device Functional Modes

Table 1 lists the functional modes of the SN74CBT3251.

Table 1. Function Table (Each Multiplexer and Demultiplexer)

INPUTS				FUNCTION
\overline{OE}	S_2	S_1	S_0	
L	L	L	L	A port = B1 port
L	L	L	H	A port = B2 port
L	L	H	L	A port = B3 port
L	L	H	H	A port = B4 port
L	H	L	L	A port = B5 port
L	H	L	H	A port = B6 port
L	H	H	L	A port = B7 port
L	H	H	H	A port = B8 port
H	X	X	X	Disconnect

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The SN74CBT3251 device can be used for a wide variety of applications, including expanding MCU GPIOs.

9.2 Typical Application

One application of the SN74CBT3251 device is to use in conjunction with a microcontroller to poll a keypad. [Figure 4](#) shows the basic schematic for such a polling system. The microcontroller uses the channel-select pins to cycle through the different channels while reading the input to see if a user is pressing any of the keys. This is a very robust setup that allows for simultaneous key presses with very little power consumption. It also uses very few pins on the microcontroller. The down side of polling is that the microcontroller must frequently scan the keys for a press.

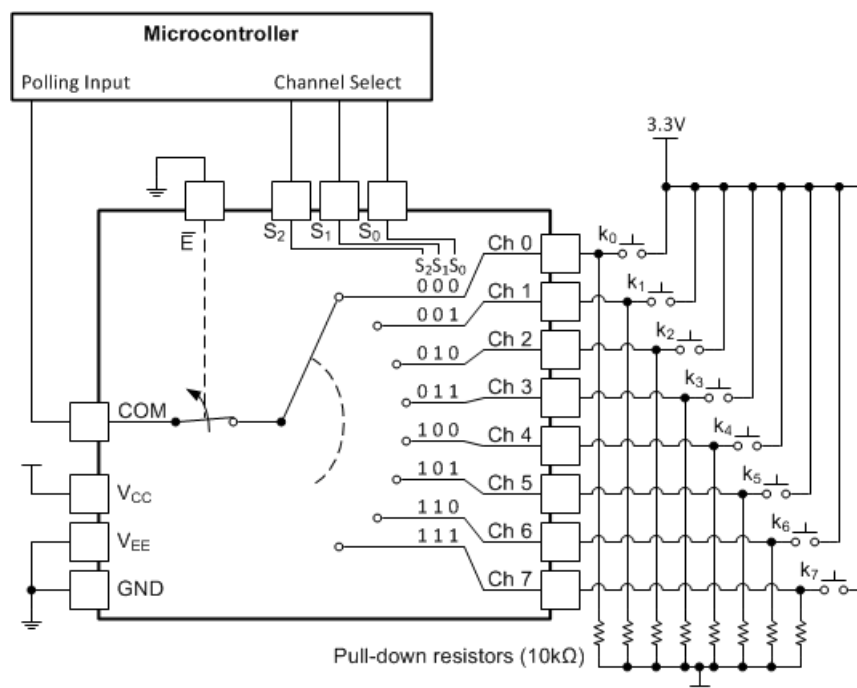


Figure 4. Keypad Polling Application

9.2.1 Design Requirements

These devices use CMOS technology and have balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits.

9.2.2 Detailed Design Procedure

1. Recommended input conditions:

- For switch time specifications, see propagation delay times in [Recommended Operating Conditions](#).
- Inputs must not be pulled below ground.
- For input voltage level specifications for control inputs, see V_{IH} and V_{IL} in [Recommended Operating Conditions](#).

Typical Application (continued)

2. Input and output current consideration:
 - Load currents must not exceed per output and must not exceed (Continuous current through V_{CC} or GND) total current for the part. These limits are located in [Absolute Maximum Ratings](#).

9.2.3 Application Curve

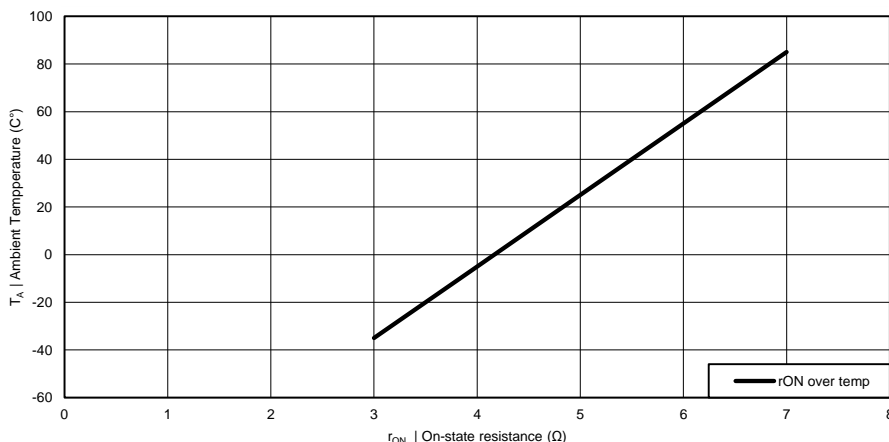


Figure 5. r_{ON} Over Temperature

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in [Recommended Operating Conditions](#).

Each V_{CC} pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1- μ F capacitor is recommended and if there are multiple V_{CC} pins then a 0.01- μ F or 0.022- μ F capacitor is recommended for each power pin. It is ok to parallel multiple bypass caps to reject different frequencies of noise. 0.1- μ F and 1- μ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

11 Layout

11.1 Layout Guidelines

When using multiple bit logic devices inputs must not ever float. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} whichever make more sense or is more convenient.

11.2 Layout Example

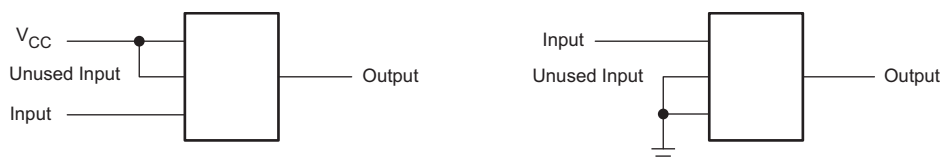


Figure 6. Layout Diagram

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation, see the following:

Implications of Slow or Floating CMOS Inputs, [SCBA004](#)

12.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.3 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

12.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74CBT3251D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3251	Samples
SN74CBT3251DBLE	OBSOLETE	SSOP	DB	16		TBD	Call TI	Call TI	-40 to 85		
SN74CBT3251DBQR	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CU251	Samples
SN74CBT3251DBQRG4	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CU251	Samples
SN74CBT3251DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU251	Samples
SN74CBT3251DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3251	Samples
SN74CBT3251DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3251	Samples
SN74CBT3251PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU251	Samples
SN74CBT3251PWLE	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI	-40 to 85		
SN74CBT3251PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU251	Samples
SN74CBT3251PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU251	Samples
SN74CBT3251RGYR	ACTIVE	VQFN	RGY	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CU251	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT3251DBQR	SSOP	DBQ	16	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
SN74CBT3251DBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74CBT3251DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74CBT3251PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74CBT3251RGYR	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT3251DBQR	SSOP	DBQ	16	2500	340.5	338.1	20.6
SN74CBT3251DBR	SSOP	DB	16	2000	367.0	367.0	38.0
SN74CBT3251DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74CBT3251PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74CBT3251RGYR	VQFN	RGY	16	3000	367.0	367.0	35.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

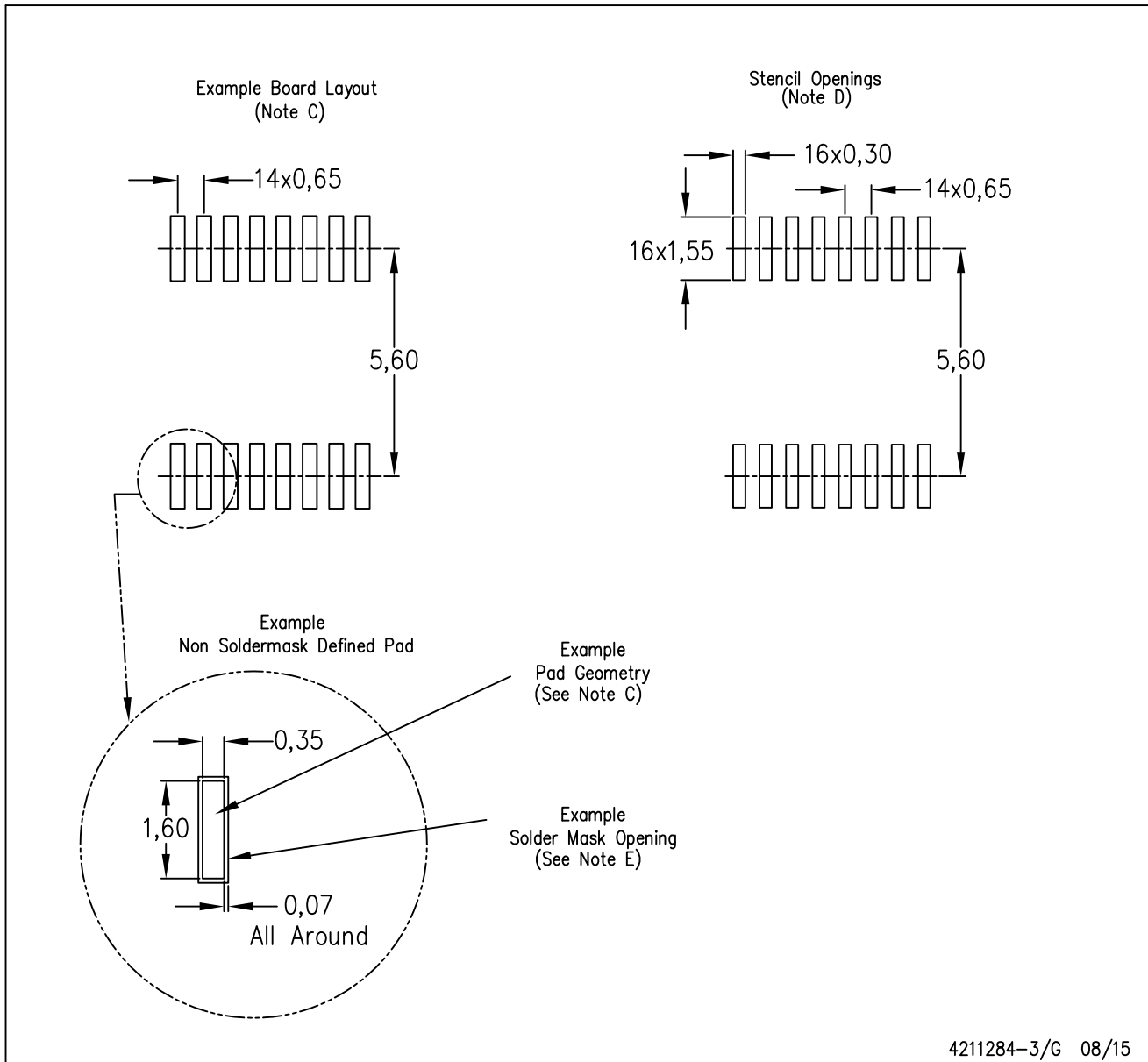
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - △ C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - △ D Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



4203539-3/I 06/2011

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- F** Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- Package complies to JEDEC MO-241 variation BA.

RGY (R-PVQFN-N16)

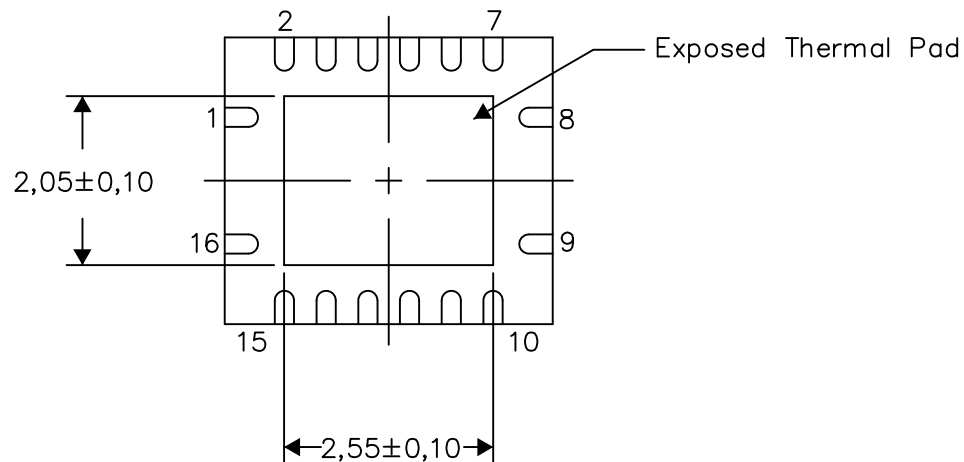
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

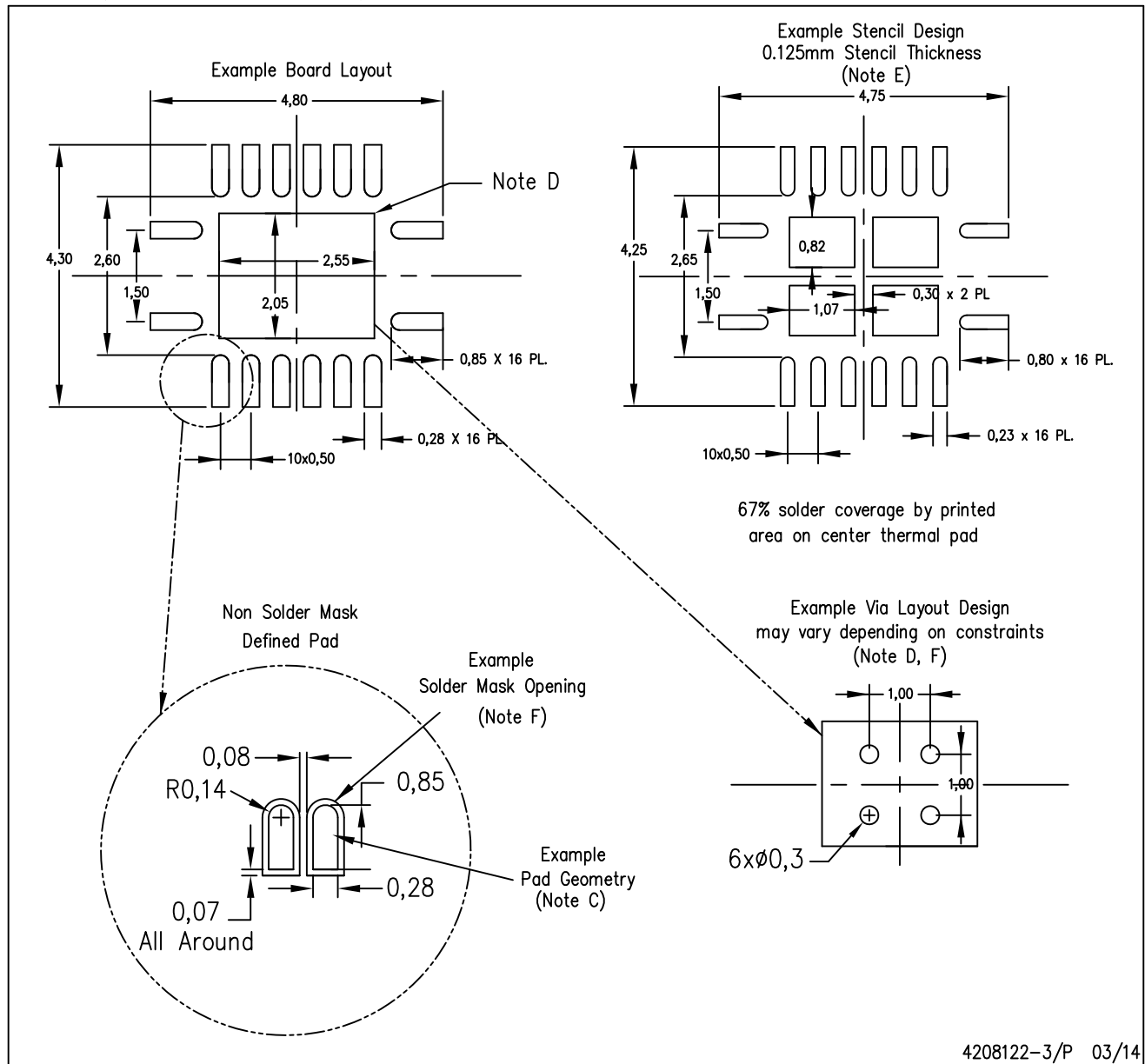
Exposed Thermal Pad Dimensions

4206353-3/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD

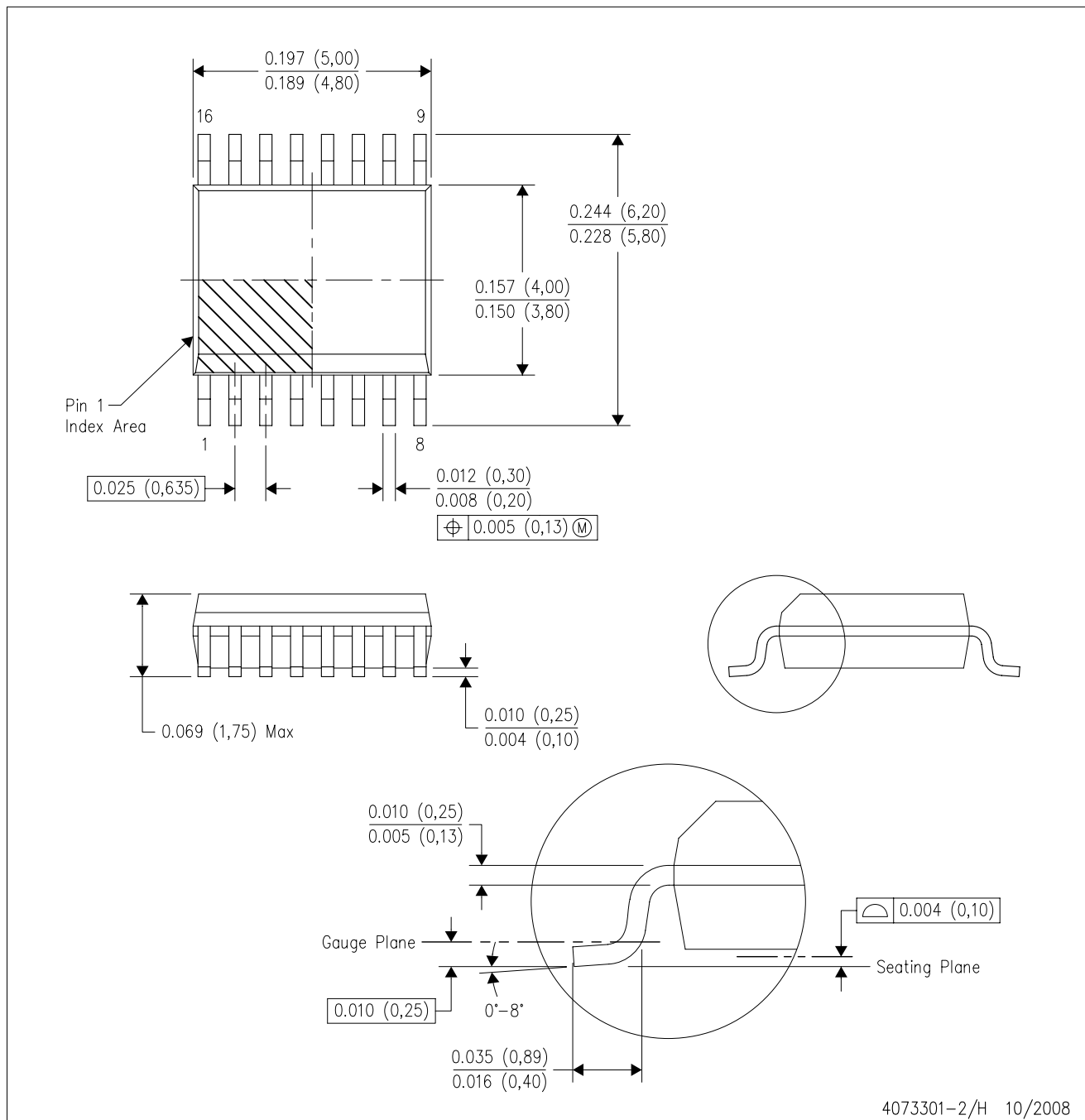


4208122-3/P 03/14

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

DBQ (R-PDSO-G16)

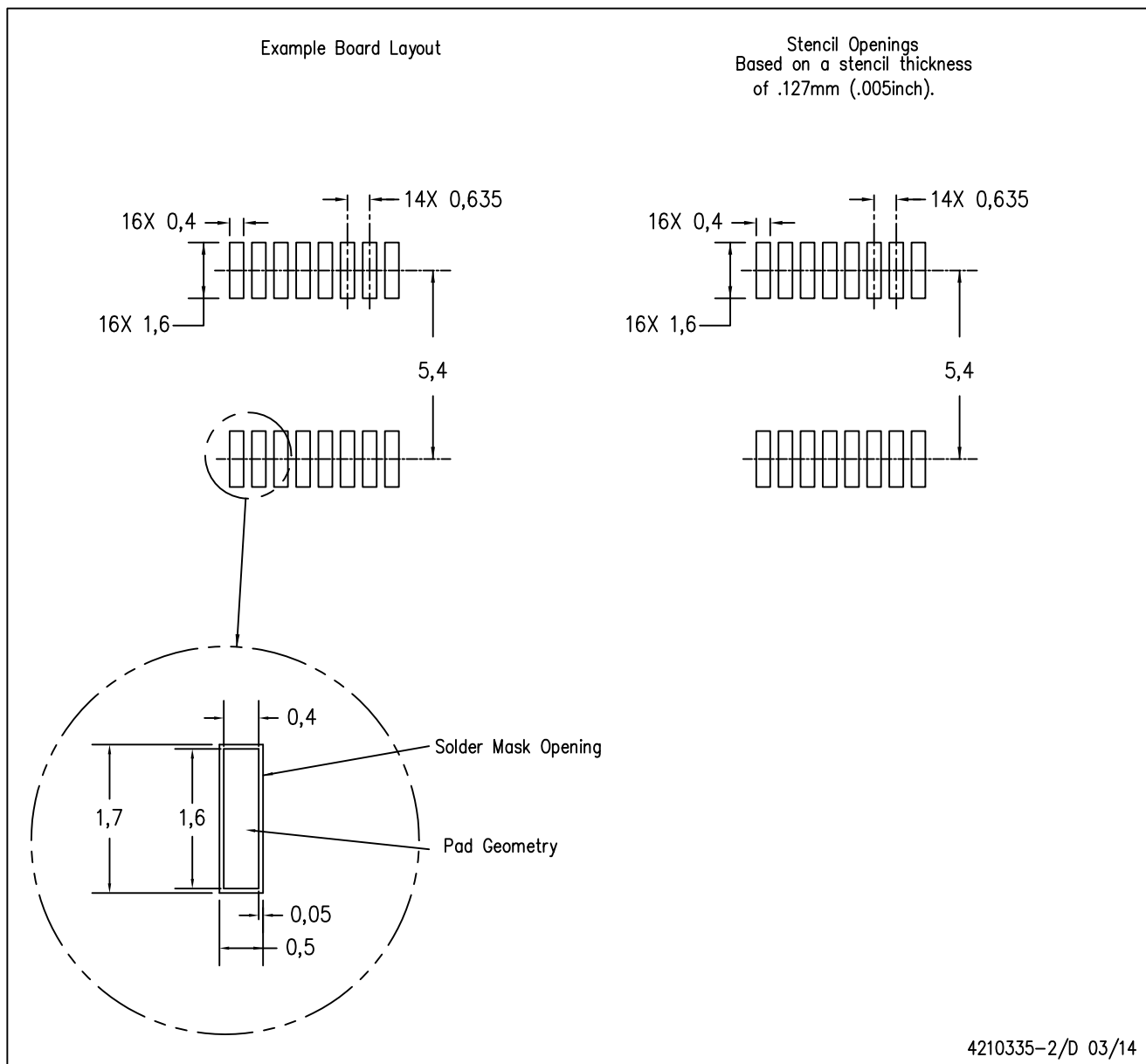
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
 - D. Falls within JEDEC MO-137 variation AB.

DBQ (R-PDSO-G16)

PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com